

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1371hvcsw#pbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.541962**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004354	1000000	8033.77734375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.153163	975000	282608.5		
		Iron (Fe)	7439-89-6	0.003770	24000	6956.2109375		
		Phosphorus (P)	7723-14-0	0.000047	300	86.7219924927		
		Zinc (Zn)	7440-66-6	0.000110	700	202.96635437		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.157090</b>	<b>1000000</b>	<b>289854.40625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.005974	1000000	11022.3232422		
		<b>External Plating Total:</b>				<b>0.005974</b>	<b>1000000</b>	<b>11022.3232422</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001257	1000000	2319.35205078		
<b>Internal Plating Total:</b>				<b>0.001257</b>	<b>1000000</b>	<b>2319.35205078</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001170	750000	2158.82397461		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000390	250000	719.607971191		
<b>Die Attach Total:</b>				<b>0.001560</b>	<b>1000000</b>	<b>2878.43188477</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.038213	103000	70508.6640625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.332045	895000	612672.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000742	2000	1369.10046387		
		<b>Encapsulation Total:</b>				<b>0.371000</b>	<b>1000000</b>	<b>684550.1875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000727	1000000	1341.4230957		
					<b>TOTAL MASS (g) :</b>	<b>0.541962</b>		